



Material Content Data Sheet



Sales Product Name		TLE75242-ESH		Issued		4. March 2019		
MA#		MA001709734						
Package		PG-TSDSO-24-21		Weight*		111.99 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.094	2.76	2.76	27624	27624
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		141	
	non noble metal	zinc	7440-66-6	0.063	0.06		565	
	non noble metal	iron	7439-89-6	1.266	1.13		11302	
wire	non noble metal	copper	7440-50-8	51.392	45.90	47.10	458894	470902
	non noble metal	copper	7440-50-8	0.815	0.73	0.73	7280	7280
	encapsulation	organic material	carbon black	1333-86-4	0.150	0.13		1344
encapsulation	plastics	epoxy resin	-	5.868	5.24		52401	
	inorganic material	silicondioxide	60676-86-0	44.139	39.41	44.78	394129	447874
leadfinish	non noble metal	tin	7440-31-5	2.820	2.52	2.52	25181	25181
plating	noble metal	silver	7440-22-4	1.279	1.14	1.14	11421	11421
glue	plastics	epoxy resin	-	0.190	0.17		1701	
	noble metal	silver	7440-22-4	0.898	0.80	0.97	8017	9718
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com